


Date: 4/17/2021

Material Number: SI823H3AB-IS1

Pkg Config.: PK0532

Detailed Device Composition 									
No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Die Attach Epoxy	0.09	2-Ethylhexyl Glycidyl Ether	2461-15-6	7.000	0.006	70000	0.0036	36
			Bisphenol F	620-92-8	12.000	0.011	120000	0.0061	61
			Epoxy Acrylate	15625-89-5	15.000	0.014	150000	0.0076	76
			Silver	7440-22-4	65.000	0.058	650000	0.0331	331
			Substituted Polyamine	68490-66-4	1.000	0.001	10000	0.0005	5
2	Bond Wire	0.22	Gold	7440-57-5	99.000	0.218	990000	0.1231	1231
			Palladium	7440-05-3	1.000	0.002	10000	0.0012	12
3	Mold Compound	102.71	Carbon Black	1333-86-4	0.300	0.308	3000	0.1742	1742
			Epoxy Resin (Proprietary)	Proprietary	8.000	8.217	80000	4.6454	46454
			Phenol Resin (Proprietary)	Proprietary	5.700	5.854	57000	3.3099	33099
			Silicon Dioxide	60676-86-0	86.000	88.331	860000	49.9382	499382
4	Leadframe	71.19	Copper	7440-50-8	96.190	68.478	961900	38.7142	387142
			Gold	7440-57-5	0.020	0.014	200	0.0080	80
			Iron	7439-89-6	2.250	1.602	22500	0.9056	9056
			Nickel	7440-02-0	1.250	0.890	12500	0.5031	5031
			Palladium	7440-05-3	0.050	0.036	500	0.0201	201
			Phosphorous	7723-14-0	0.100	0.071	1000	0.0402	402
			Silver	7440-22-4	0.020	0.014	200	0.0080	80
			Zinc	7440-66-6	0.120	0.085	1200	0.0483	483
5	Die	0.89	Aluminum	7429-90-5	0.163	0.001	1630	0.0008	8
			Copper	7440-50-8	0.001	0.000	10	0.0000	0
			Silicon	7440-21-3	99.726	0.888	997260	0.5018	5018
			Tungsten	7440-33-7	0.110	0.001	1100	0.0006	6
6	Die	1.78	Aluminum	7429-90-5	0.163	0.003	1630	0.0016	16
			Copper	7440-50-8	0.001	0.000	10	0.0000	0
			Silicon	7440-21-3	99.726	1.775	997260	1.0036	10036
			Tungsten	7440-33-7	0.110	0.002	1100	0.0011	11
	Total Unit Weight =	176.88				176.88		100.0000	1000000